



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: L0307-02 DATE: 8/1/03 Product Affected: IDT74FCT3244, IDT74FCT3245 IDT74FCT244T, IDT74FCT245T Date Effective: October 31, 2003	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark <input checked="" type="checkbox"/> Date Code Prefix (Stepping) change. Please see attachment for details. <input type="checkbox"/> Other
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Contact: Bimla Paul Title: Quality Assurance Manager Phone #: (408)-654-6419 Fax #: (408)-492-8362 E-mail: bimla.paul@idt.com	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Available upon request.
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology	
<input type="checkbox"/> Wafer Fabrication Process	Device stepping (revision) change from "PB" to "Z" on selected Logic products.
<input type="checkbox"/> Assembly Process	There is no change in die technology.
<input type="checkbox"/> Equipment	
<input type="checkbox"/> Material	Please see attachment for the affected part numbers and qual data.
<input type="checkbox"/> Testing	
<input type="checkbox"/> Manufacturing Site	
<input type="checkbox"/> Data Sheet	
<input checked="" type="checkbox"/> Other	

RELIABILITY/QUALIFICATION SUMMARY:
Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:
 IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____	DATE: _____
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PCN Type: Die Revision Change

Data Sheet Change: None

Detail of Change: Device stepping (revision) change from "PB" to "Z" on selected Logic products. There is no change in die technology or fab location.

The following devices are affected by this change. All packages and speed grades are affected.

Part Number	Old Stepping	New Stepping
IDT74FCT3244	PB	Z
IDT74FCT3245	PB	Z
IDT74FCT244T	PB	Z
IDT74FCT245T	PB	Z

Conversion Schedule:

Die Revision

Z Stepping

Sample Availability:

August 15, 2003

Production Shipment:

October 31, 2003



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Qualification Plans: Following reliability tests were performed on the process family. The qualification results are as follow:

Test Description	Test Method	Required Sample/ # Fails	Process Family Data	Z Stepping Data
Operating Life Test: Dynamic 1000 hrs @ 125°C or equivalent	Mil-Std 883 Method 1005	116/0	116/0	ECD Sept 15, 03
Bake & Ball Shear	EIA/JESD 22 B116	5/0	5/0	
Temp Cycle -65°C to +150°C, 500 Cyc	JESD 22 A104	45/0	45/0	
ESD Human Body Model	Mil-Std 883 Method 3015	3/0	3000V	ECD Sept 15, 03
ESD Charged Device Model	JEDEC 22-101	3/0	1000V	ECD Sept 15, 03
Latch up: (Tested to 1.5X Vcc)	EIA/JESD STD-78	10/0	10/0	ECD Sept 15, 03

ECD = Estimated Completion Date

Characterization Data:

Characterization data is available upon request.